Date Created : **2007/10/11**
Date Issued On : **2007/11/02**
PCN# : **Q4074105**

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A Final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

Technical Contact:
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Phone:

PCN Originator:
Name: Sun, Brian
E-mail: Brian.Sun@fairchildsemi.com
Phone:

Implementation of change:
Expected 1st Device Shipment Date: 2008/02/14

Earliest Year/Work Week of Changed Product: 0810

Change Type Description: Die Shrink

Description of Change (From): Two type of die dimension: 0.35mm * 0.35mm for 2.0-20V DO35 product; 0.45mm * 0.45mm for 22-75V DO35 product.

Description of Change (To): Consolidate to one die dimension 0.32 mm * 0.32 mm for 2.4V~75V DO35 product. There is no difference in package dimension, process and electrical specification after change.

Reason for Change : Consolidate wafer process to improve quality

Qual/REL Plan Numbers : Q20070376

Qualification :

To qualify the small die(0.32mm*0.32mm) to replace the die(0.35mm*0.35mm,0.45*0.45mm) which is used in the current DO-35 package.

Qualification Stress Test and Sample Size Detail

Device #1	BZX55C10
Package:	
#Leads:	

Environment Stress Detail:

				Readpoints			Samples
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A
HTOL			150C	168	500	1000	77

HTRB		JESD22-A108	150C, 80% of re-lated BV	168	500	1000	77
HTSL		JESD22-A103	175C	168	500	1000	77
TMCL1		JESD22-A104	-65C, 150C	500	1000		77

Device #2	BZX55C3V3
Package:	
#Leads:	

Environment Stress Detail:

				Readpoints			Samples
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A
HTOL			150C	168	500	1000	77
HTRB		JESD22-A108	150C, 80% of re-lated BV	168	500	1000	77
HTSL		JESD22-A103	175C	168	500	1000	77
TMCL1		JESD22-A104	-65C, 150C	500	1000		77

Device #3	BZX55C51
Package:	-1
#Leads:	-1

Environment Stress Detail:

				Readpoints			Samples
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A
HTOL			150C	168	500	1000	77
HTRB		JESD22-A108	150C, 80% of re-lated BV	168	500	1000	77
HTSL		JESD22-A103	175C	168	500	1000	77
TMCL1		JESD22-A104	-65C, 150C	500	1000		77

Product Id Description :

Affected FSIDs :

1N5985B	1N5986B	1N5987B
1N5988B	1N5989B	1N5990B
1N5991B	1N5992B	1N5993B
1N5994B	1N5995B	1N5996B
1N5997B	1N5998B	1N5999B
1N6000B	1N6001B	1N6002B
1N6003B	1N6004B	1N6005B
1N6006B	1N6007B	1N6008B
1N6009B	1N6010B	1N6011B
1N6012B	1N6013B	1N6014B
1N6015B	1N6016B	1N6017B
1N6018B	BZX55C10	BZX55C11
BZX55C12	BZX55C13	BZX55C15
BZX55C16	BZX55C18	BZX55C20
BZX55C22	BZX55C24	BZX55C27
BZX55C2V4	BZX55C2V7	BZX55C30
BZX55C33	BZX55C36	BZX55C39
BZX55C3V0	BZX55C3V3	BZX55C3V6
BZX55C3V9	BZX55C43	BZX55C47

BZX55C4V3	BZX55C4V7	BZX55C51
BZX55C56	BZX55C5V1	BZX55C5V6
BZX55C6V2	BZX55C6V8	BZX55C7V5
BZX55C8V2	BZX55C9V1	BZX79C10
BZX79C11	BZX79C12	BZX79C13
BZX79C15	BZX79C16	BZX79C18
BZX79C20	BZX79C22	BZX79C24
BZX79C27	BZX79C2V4	BZX79C2V7
BZX79C30	BZX79C33	BZX79C36
BZX79C39	BZX79C3V0	BZX79C3V3
BZX79C3V6	BZX79C3V9	BZX79C43
BZX79C47	BZX79C4V3	BZX79C4V7
BZX79C51	BZX79C56	BZX79C5V1
BZX79C5V6	BZX79C6V2	BZX79C6V8
BZX79C7V5	BZX79C8V2	BZX79C9V1